



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Masatake NAKANO et al.

Group Art Unit: 1763

Application No.: 09/857,569

Examiner: G. Goudreau

Filed: June 7, 2001

Docket No.: 109716

For: METHOD FOR PRODUCING BONDING WAFER AND BONDING WAFER

STATEMENT OF SUBSTANCE OF INTERVIEW UNDER MPEP §713.04

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

A personal interview was held with Examiner Goudreau on December 2, 2003 in connection with the above-identified Application. Applicants thank the Examiner for the courtesies extended to Applicants' representative during the personal interview.

During the personal interview, the distinguishing features of the invention with respect to the references applied in the August 19, 2003, Office Action were discussed. The points presented paralleled those found in the Amendment filed on November 18, 2003.

Specifically, it was discussed and agreed that claim 17 and its dependent claims 18 and 19 are allowable as claim 17 has been amended to include the allowable features indicated in the August 19, 2003, Office Action.

Regarding claims 14-16 and 20-22, it was discussed that none of the applied references disclosed a method for producing a bonding wafer comprising forming an oxide film by subjecting the wafer to bonding heat treatment in an oxidizing atmosphere, masking

at least portions of the top surface other than peripheral portions to be removed, and removal of the peripheral portion of the thin film is attained by etching the wafer, as recited in claim 14, and therefore, that claims 14-16 are allowable.

Further, it was discussed that none of the applied references disclosed the removal of the peripheral portion of the thin film is attained by polishing only the peripheral portion while supplying pure water to the center of the wafer, as recited in claim 20, and therefore, that claims 20-22 are allowable.

The Examiner stated the points will be fully and fairly considered.

Respectfully submitted,



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Date: December 16, 2003

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